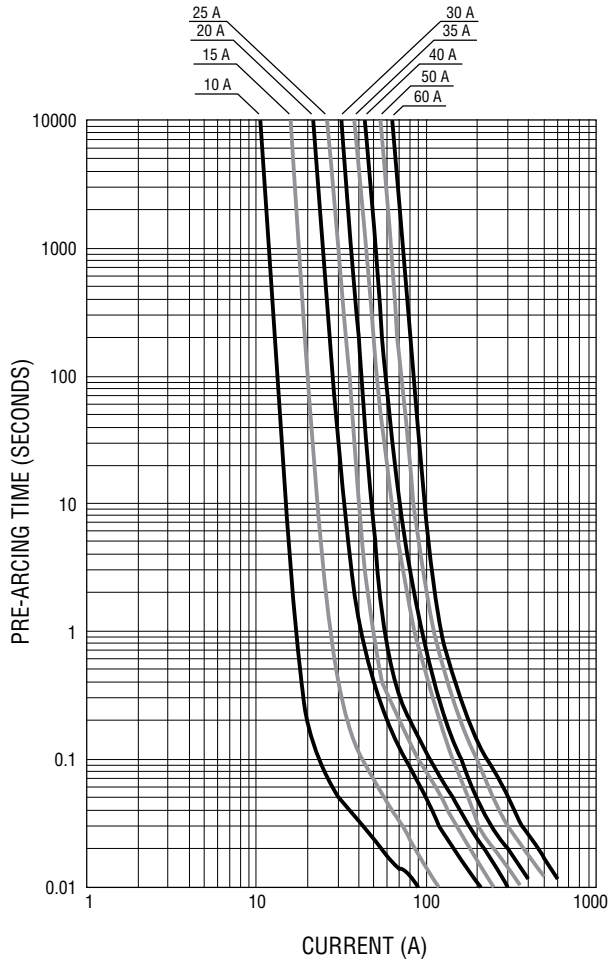


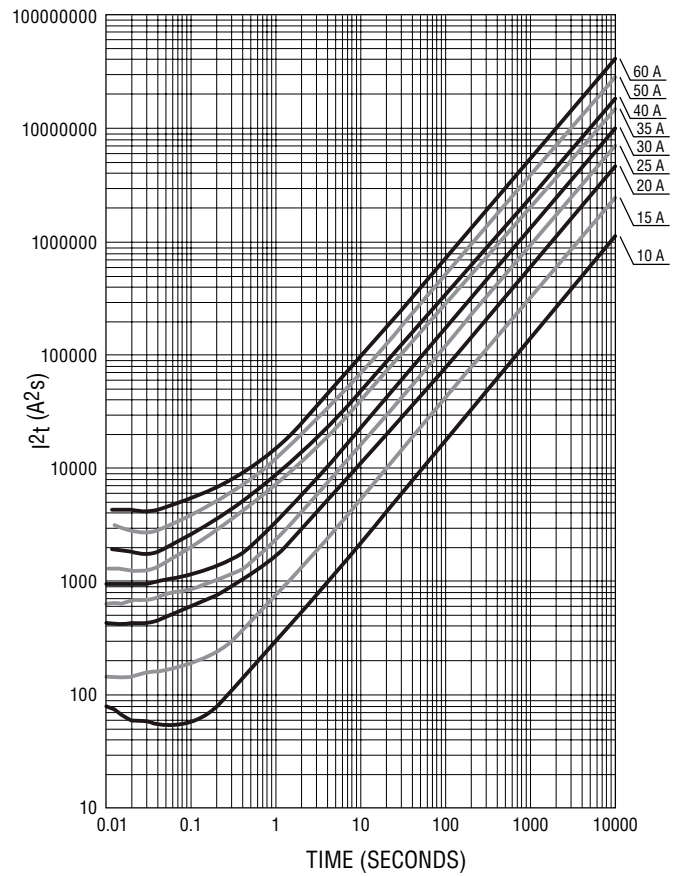
SF-3812F-T Series – Fast Acting SMD Fuses

BOURNS®

Average Pre-Arcing Time vs. Current Curves



Average I^2t vs. t Curves



Specifications are subject to change without notice.

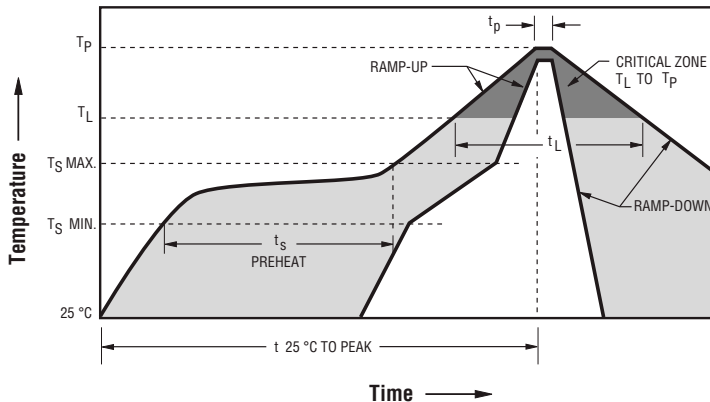
Users should verify actual device performance in their specific applications.

The products described herein and this document are subject to specific legal disclaimers as set forth on the last page of this document, and at www.bourns.com/docs/legal/disclaimer.pdf.

SF-3812F-T Series – Fast Acting SMD Fuses

BOURNS®

Solder Reflow Recommendations

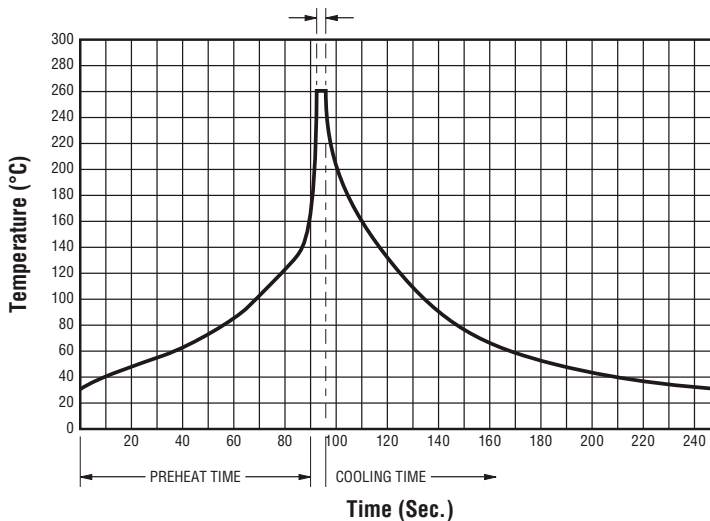


Profile Feature	Pb-Free Assembly
Preheat / Soak:	
Temperature Min. (T_{smin})	150 °C
Temperature Max. (T_{smax})	200 °C
Time (t_s) from (T_{smin} to T_{smax})	60~180 seconds
Ramp Up Rate (T_L to T_p)	3 °C / second max.
Ramp Up Rate (T_{smax} to T_L)	5 °C / second max.
Liquidous Temperature (T_L)	217 °C
Time (t_L) maintained above T_L	60~150 seconds
Peak Package Body Temperature (T_p)	260 °C +0/-5 °C
Time within 5 °C of actual peak temperature (T_p)	10~30 seconds*
Ramp Down Rate (T_p to T_L)	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.
Do not exceed	260 °C

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

Solder Wave Recommendations

Peak Temperature (Dwell Time)



Profile Feature	Pb-Free Assembly
Preheat:	
Temperature Max. (T_{smax})	150 °C
Time (Min. to Max.)	60~90 seconds
Solder Pot Temperature	260 °C max.
Solder Dwell Time	2~3 seconds

Specifications are subject to change without notice.

Users should verify actual device performance in their specific applications.

The products described herein and this document are subject to specific legal disclaimers as set forth on the last page of this document, and at www.bourns.com/docs/legal/disclaimer.pdf.